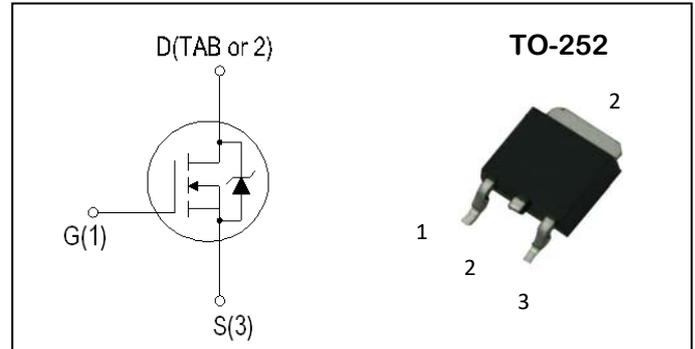


## N-Channel Enhancement Mode Field Effect Transistor

### PRODUCT SUMMARY

$V_{DSS}$	$I_D$	$R_{DS(ON)}$ (m $\Omega$ )
60V	30A	26m $\Omega$



### Features:

- Low Gate Charge for Fast Switching Application
- Low  $R_{DS(ON)}$  to Minimize Conductive Loss
- 100% EAS Guaranteed
- Optimized  $V_{(BR)DSS}$  Ruggedness
- Lead-Free, RoHS Compliant

### Description:

The ADM30N06E uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise specified )

Symbol	Parameter		Ratings	Unit
<b>Common Ratings</b>				
$V_{DSS}$	Drain-Source Voltage		60	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20\text{V}$	
$T_J$	Maximum Junction Temperature		175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-55 to 175	$^\circ\text{C}$
$I_S$	Diode Continuous Forward Current	$T_C = 25^\circ\text{C}$	25	A
<b>Mounted on Large Heat Sink</b>				
$I_{DM}$	300 $\mu\text{s}$ Pulse Drain Current Tested <sup>(2)</sup>	$T_C = 25^\circ\text{C}$	70	A
$I_D$	Continuous Drain Current <sup>(1)</sup>	$T_C = 25^\circ\text{C}$	30	A
		$T_C = 100^\circ\text{C}$	17	A
$P_D$	Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	50	W

### Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{thJC}$	Thermal resistance junction-case max <sup>(1)</sup>	3.0	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance junction-ambient max <sup>(1)</sup>	70	$^\circ\text{C}/\text{W}$

## Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
<b>On/off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	--	--	1	uA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA	1	--	3.0	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance <sup>(2)</sup>	V <sub>GS</sub> = 10V, I <sub>DS</sub> =15A	--	26	30	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, Frequency=1MHz	--	1890	--	pF
C <sub>oss</sub>	Output Capacitance		--	168	--	
C <sub>rss</sub>	Reverse Transfer Capacitance		--	132	--	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30V, I <sub>D</sub> = 2A, V <sub>GS</sub> = 10V, R <sub>GEN</sub> =3Ω	--	7	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	3.2	--	
t <sub>d(OFF)</sub>	Turn-off Delay Time		--	19.2	--	
t <sub>f</sub>	Turn-off Fall Time		--	3.2	--	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =48V, V <sub>GS</sub> = 10V, I <sub>DS</sub> =10A	--	49	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	8	--	
Q <sub>gd</sub>	Gate-Drain Charge		--	16	--	
<b>Avalanche Characteristics</b>						
EAS	Single Pulse Avalanche Energy <sup>(3)</sup>	L=0.5mH , V <sub>DS</sub> =30V , R <sub>GEN</sub> =25Ω , V <sub>GS</sub> = 10V	100	--	--	mJ
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>(2)</sup>	I <sub>SD</sub> = 10A, V <sub>GS</sub> = 0	--	--	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =10A, dI <sub>SD</sub> /dt=100A/μs	--	35	--	ns
q <sub>rr</sub>	Reverse Recovery Charge		--	43	--	nC

### NOTES:

1. Surface Mounted on FR4 Board, t ≤ 10 sec.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The Min. value is 100% EAS tested guarantee.

## Typical Performance Characteristics

Figure 1: On-Region Characteristics

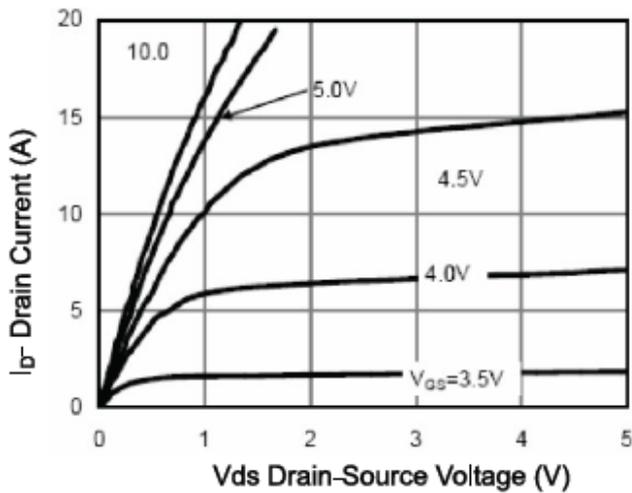


Figure 2: Transfer Characteristics

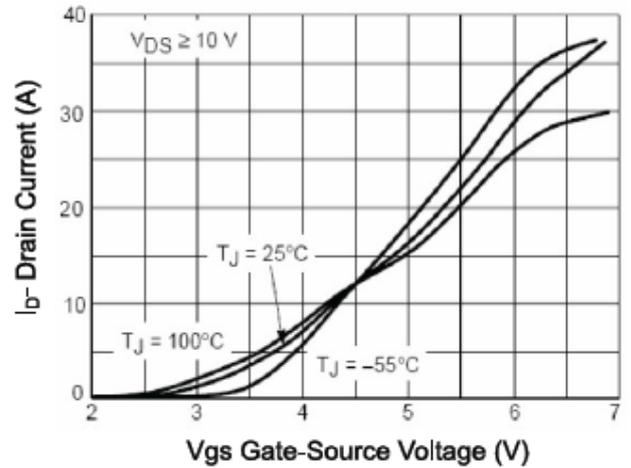


Figure 3: Rdson- Drain Current

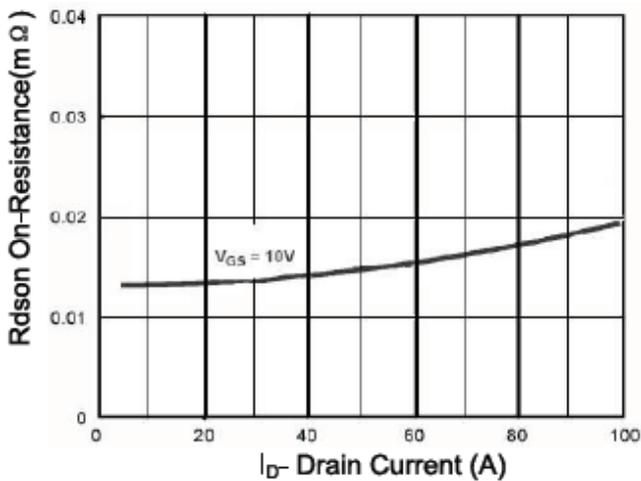


Figure 4: Rdson-Junction Temperature

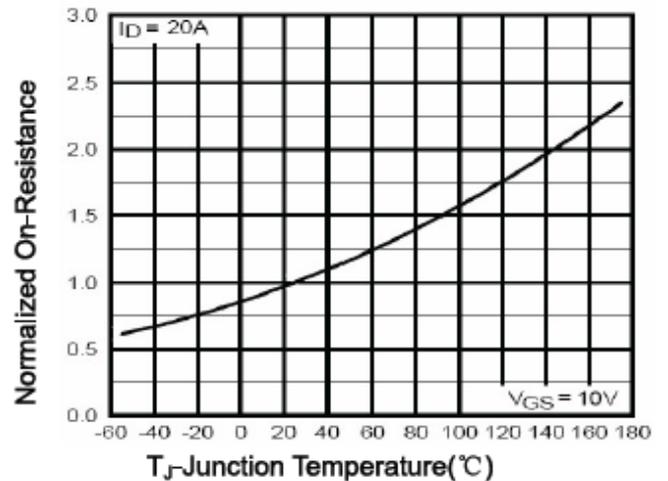


Figure 5: Source- Drain Diode Forward

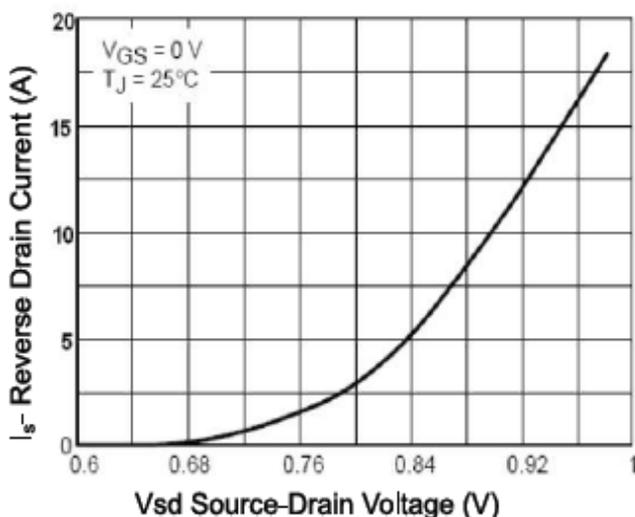


Figure 6: Gate Charge Characteristics

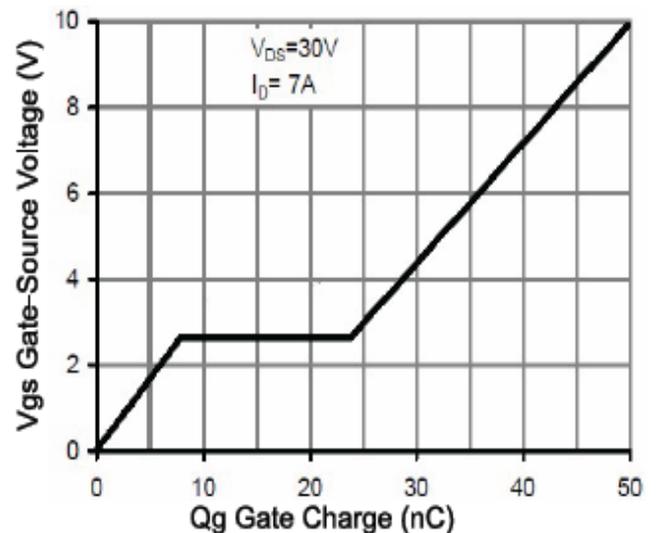


Figure 7: Capacitance vs Vds

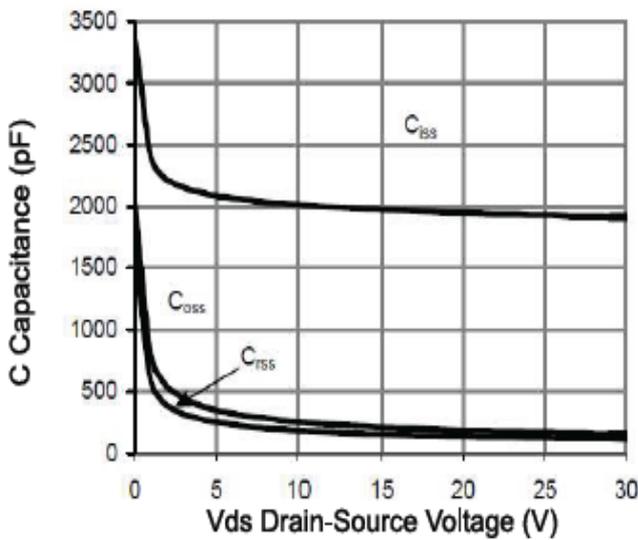


Figure 8: Safe Operation Area

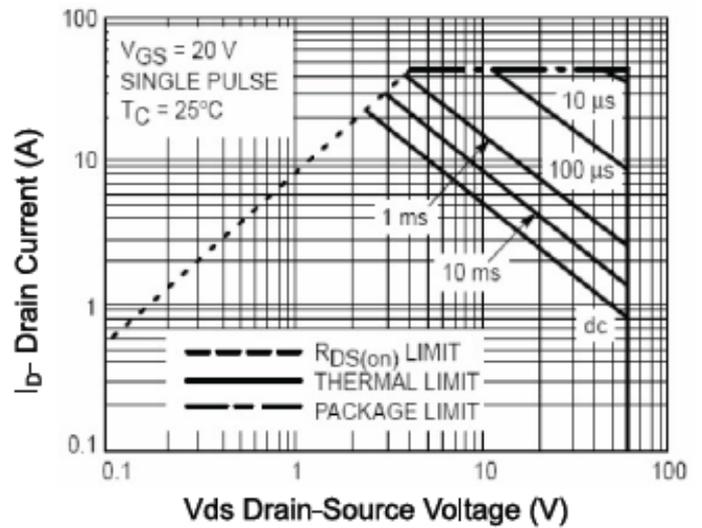


Figure 9: BV<sub>DSS</sub> vs. Junction Temperature

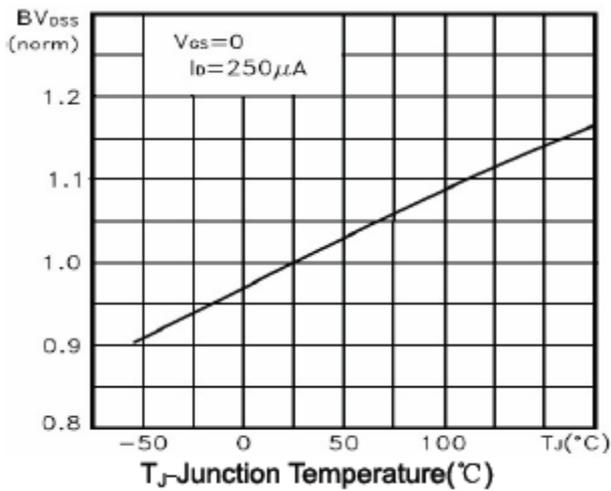


Figure 10: On-Resistance vs. Gate-Source Voltage

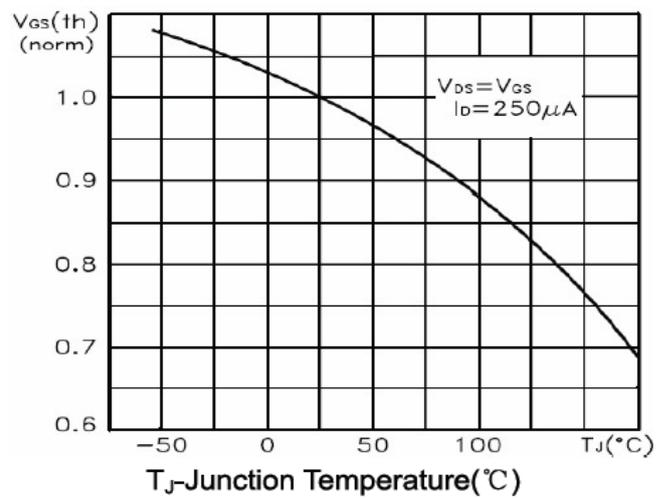
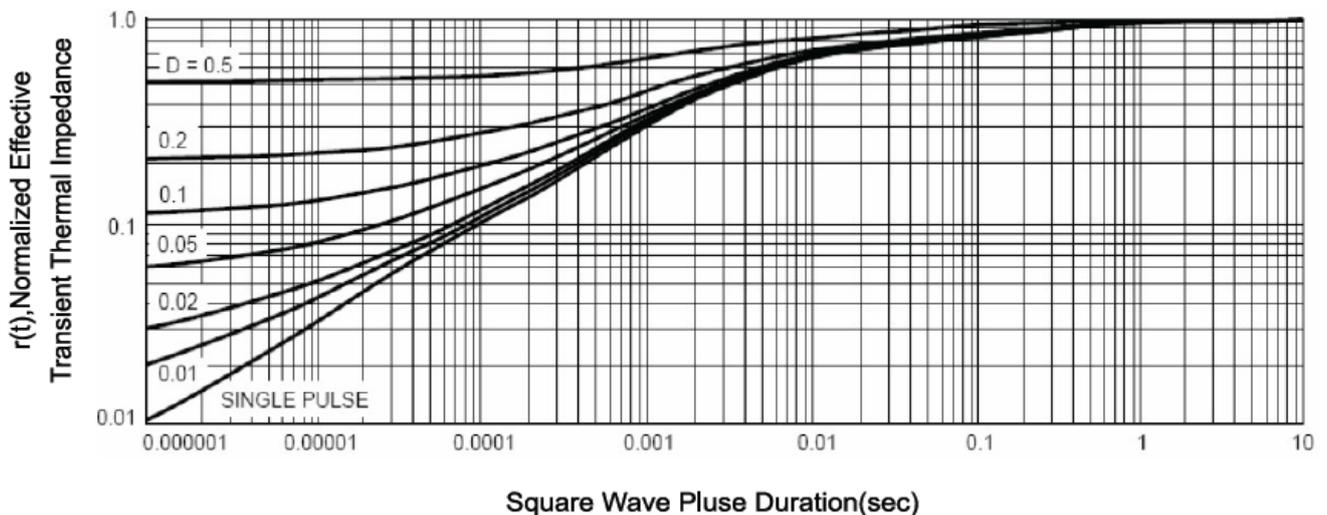
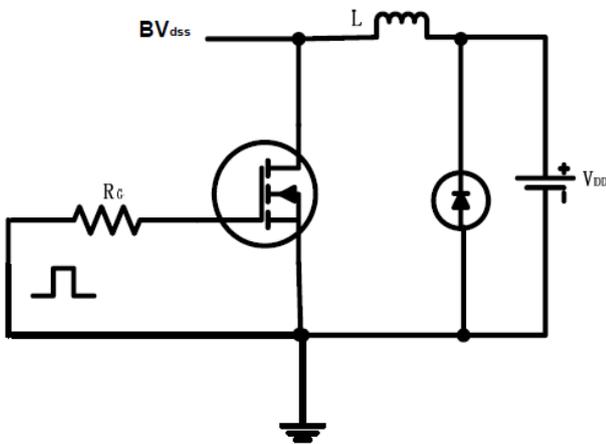


Figure 11: Normalized Maximum Transient Thermal Impedance

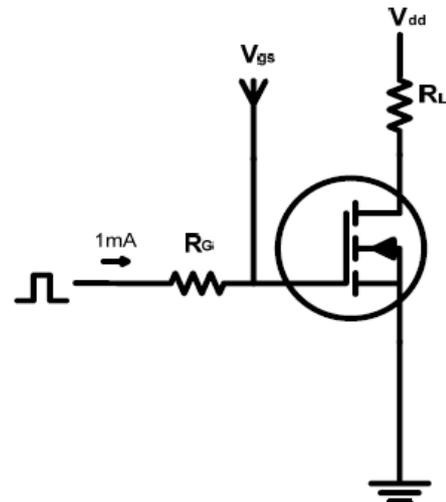


## Test circuits and Waveforms

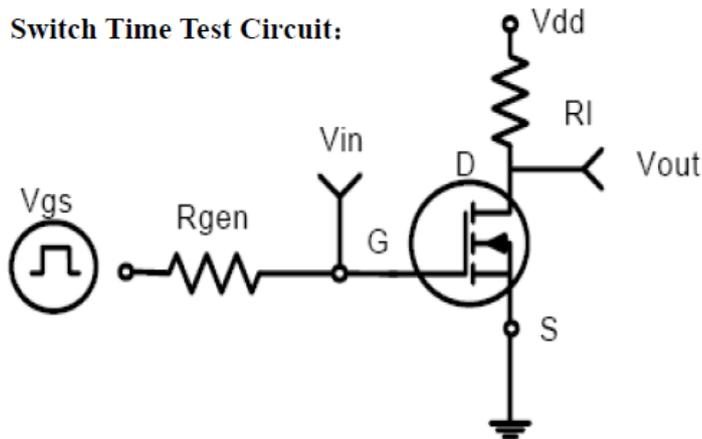
EAS test circuits:



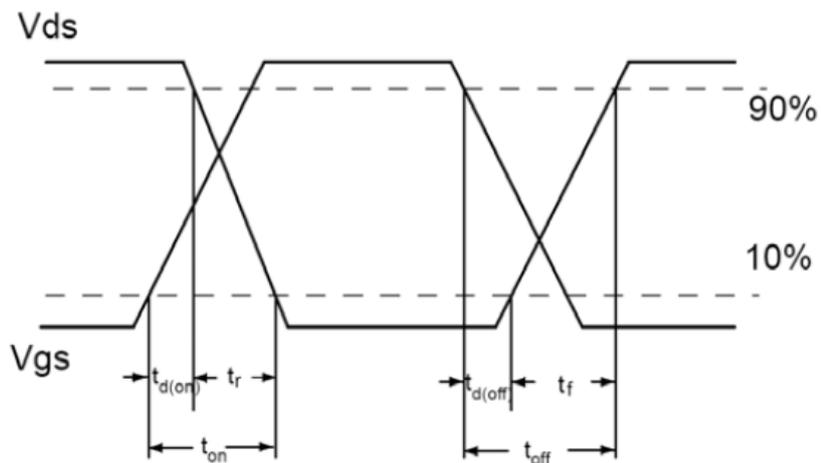
Gate charge test circuit:



Switch Time Test Circuit:

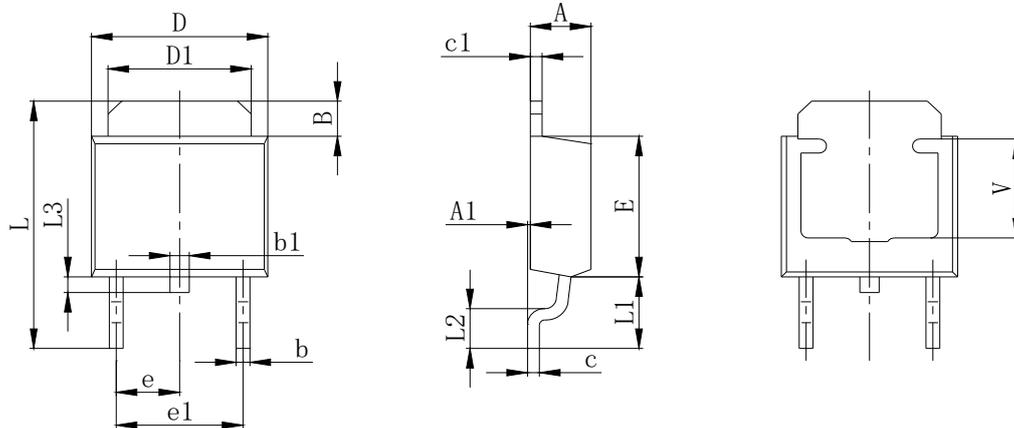


Switch Waveforms:



## PACKAGE MECHANICAL DATA

### TO-252 Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF.		0.150 REF.	